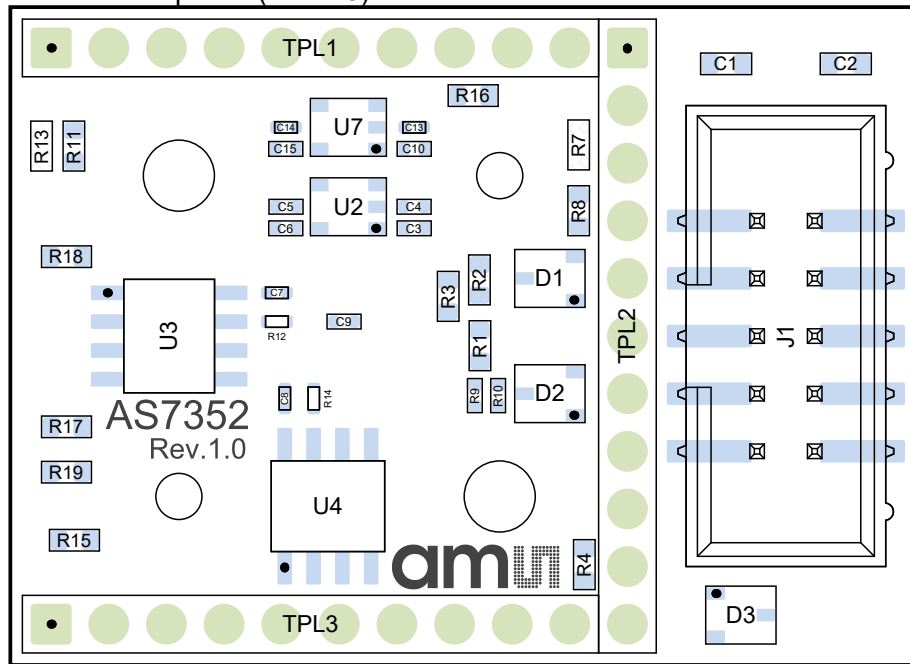
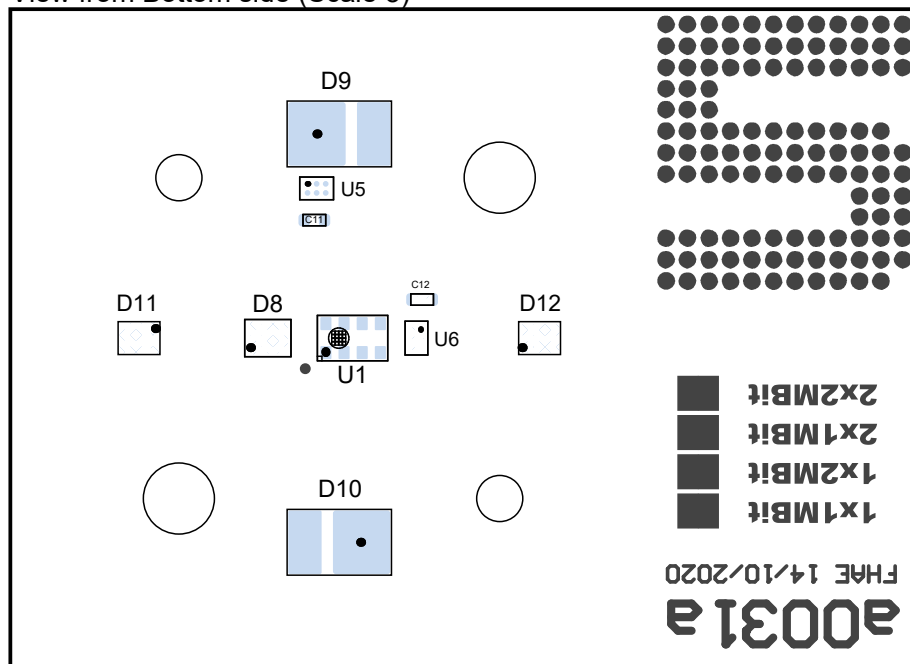


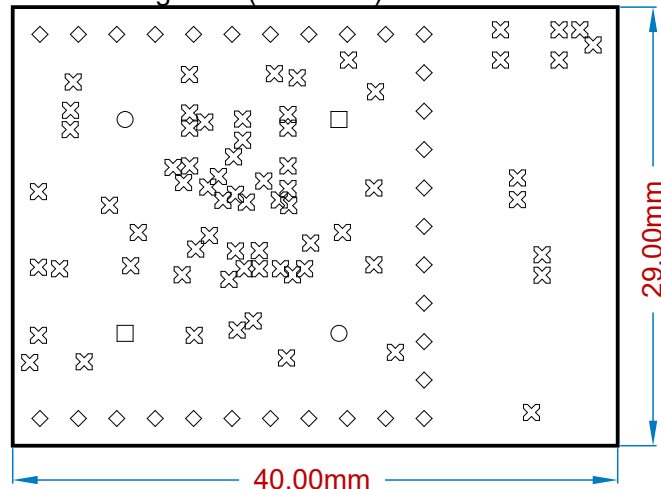
View from Top side (Scale 3)



View from Bottom side (Scale 3)



Drill Drawing View (Scale 2:1)



Drill Table

Symbol	Count	Hole Size	Plated	Hole Tolerance
✕	69	0.20mm	Plated	
◇	31	1.00mm	Plated	
□	2	2.10mm	Non-Plated	+0.10mm/-0.00mm
○	2	3.20mm	Non-Plated	+0.10mm/-0.00mm
	104 Total			

- 1.55mm $\pm 10\%$ 4-Layer FR4 (MLL4)
- manufactured with IPC Claas 2
- Technology: 150 μ m TrackWith/
TrackTrack
smallest drill: 200 μ m
- Prepreg and Core Thickness is free to defined
- outline is milled and v-cutted
- finished surface is ENIG
- Silkscreen color is white and made in high resoluion (more than 200 μ m)
- Solder Mask color is black.
Respect .GM3 and .GM4 Files to open black solder mask. In this area, only the green base solder mask is used.
- check Gerber files against the IPC-D-356A.ipc netlist file
- Questions to:
ams Sensors Germany GmbH
Fernando Hädrich
e-mail:
fernando.haedrich@ams.com
Phone: +49 3641 280935



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Product: AS7352

Variant 2x2MBit EEPROM

PCB Name: a0031a_AWS EVM AS7352 Yuji EE TMP.PcbDoc

Rev 1.0.0

Application Engineer: FHAEE

Release Date: 14/10/2020

Sheet Name: a0031a0_AWS EVM AS7352 Yuji EE TMP.PCBDwf

Page Size: A4

Last Save Date / Time: 14.10.2020 / 14:43

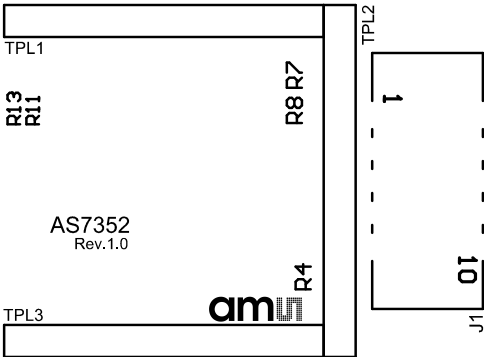
Doc. Scale:

Project: a003_AWS

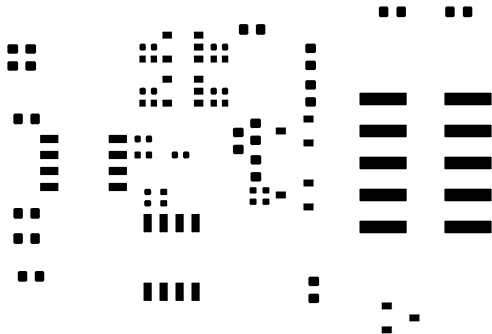
Sheet 1 of 1

1:1
Millimeters

Top Silk

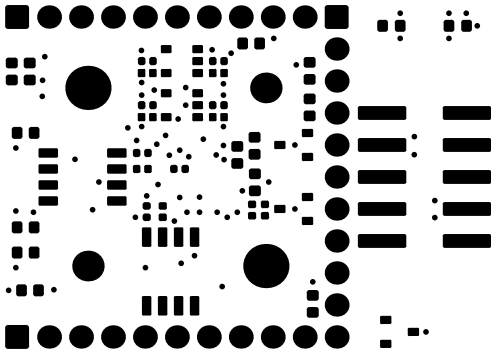


Top Paste

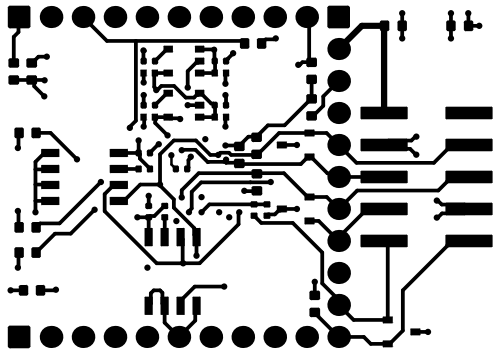


Top Solder no black

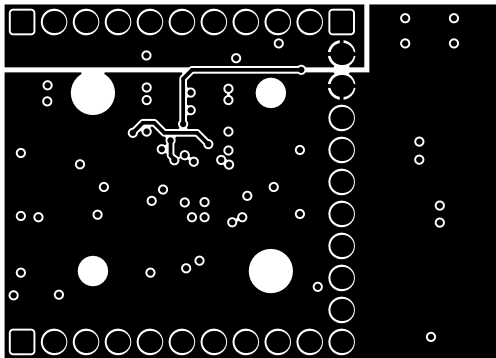
Top Solder



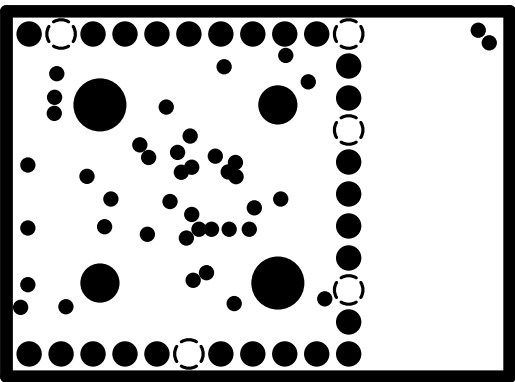
Top Layer



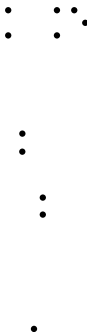
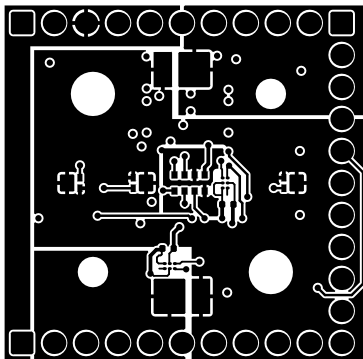
Inner 1



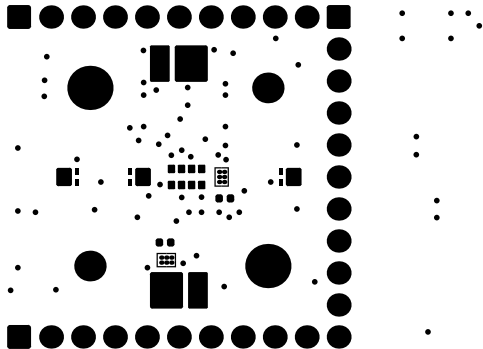
Inner 2



Bottom Layer



Bottom Solder



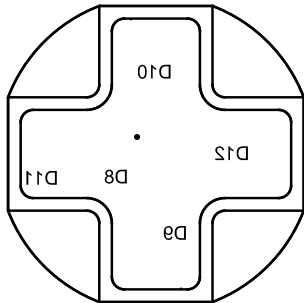
Bottom Solder no black



Bottom Paste

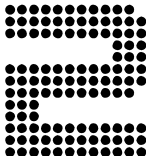


Bottom Silk



900319

FHE 14\10\2020



Board Outline

